



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-11-20
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC10H065DI	HZUR*3D091T6	A	SH1A	2017-11-20
	Amount	UoM	Unit type	ST ECOPACK Grade
	2170.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	Not Applicable		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10,15.5,4.5	2	Through-hole	
Comment				

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 21st October 2016			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.04	Die	16
Lead	5.18	Soft solder	2388

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HZUR*3D091T6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.967	mg	supplier	die	Silicium carbide	409-21-2		4.142	mg	971844	1909
				supplier	metallization	Aluminium (Al)	7429-90-5		0.024	mg	5631	11
				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	1514	2
				supplier	passivation	Nickel (Ni)	7440-02-0		0.019	mg	4458	9
				supplier	metallization	Silver (Ag)	7440-22-4		0.041	mg	9620	19
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	235	0
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	235	0
				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	939	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.016	mg	3754	7
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.010	mg	2346	5
Leadframe	Copper & its alloys	1558.055	mg	supplier	alloy	Copper (Cu)	7440-50-8		1556.029	mg	998700	717064
				supplier	alloy	Iron (Fe)	7439-89-6		0.717	mg	460	330
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		1.309	mg	840	603
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high me	5.181	mg	849902	2388
Soft solder	Solder	6.096	mg	JIG - R	solder	Antimony (Sb)	7440-36-0		0.610	mg	100066	281
				supplier	solder	Tin (Sn)	7440-31-5		0.305	mg	50033	141
				supplier	wire	Aluminium (Al)	7429-90-5		1.231	mg	1000000	567
Encapsulation	Other Organic Materials	596.147	mg	supplier	mold compound	Silica, vitreous	60676-86-0		453.072	mg	760000	208789
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		60.807	mg	102002	28022
				supplier	mold compound	Phenol resin	9003-35-4		35.769	mg	60000	16483
				supplier	mold compound	Others	Proprietary		29.807	mg	49999	13736
				supplier	mold compound	Metal hydroxide	Proprietary		11.923	mg	20000	5494
				supplier	mold compound	Carbon black	1333-86-4		4.769	mg	8000	2198
connections coating	Solder	4.209	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.209	mg	1000000	1940